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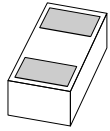
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# BB179BLX

## UHF variable capacitance diode

Rev. 2 — 5 September 2011

Product data sheet

## 1. Product profile

### 1.1 General description

The BB179BLX is a planar technology variable capacitance diode in a SOD882T ultra small leadless plastic SMD package. The excellent matching performance is achieved by gliding matching and a Direct Matching Assembly (DMA) procedure.

### 1.2 Features and benefits

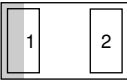

- Excellent linearity
- Excellent matching to 2 % DMA
- Ultra small leadless SMD package
- $C_{d(28V)}$ : 2.1 pF;  $C_{d(1V)}$  to  $C_{d(28V)}$  ratio typical 9
- Low series resistance

### 1.3 Applications

- Voltage Controlled Oscillators (VCO)
- Electronic tuning in UHF television tuners

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode <a href="#">[1]</a>		
2	anode		

Transparent top view

sym008

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
BB179BLX	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.4 mm	SOD882T



## 4. Marking

Table 3. Marking codes

Type number	Marking code
BB179BLX	L5

## 5. Limiting values

Table 4. Limiting values

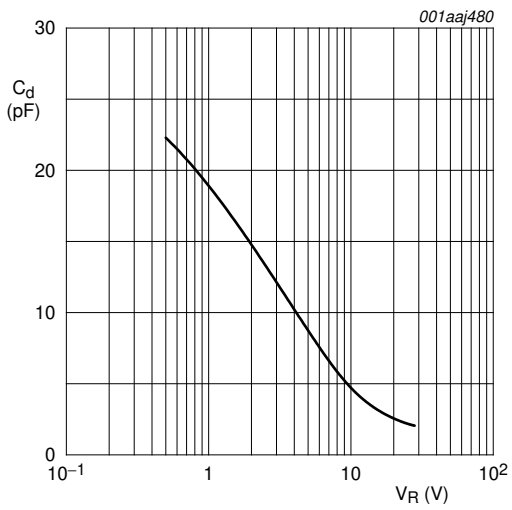
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage		-	32	V
$I_F$	forward current		-	20	mA
$T_{stg}$	storage temperature		-55	+150	°C
$T_j$	junction temperature		-55	+125	°C

## 6. Characteristics

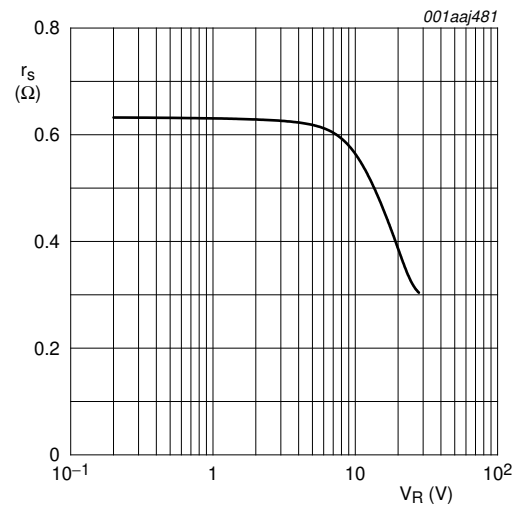
Table 5. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_R$	reverse current	see <a href="#">Figure 3</a>				
		$V_R = 30$ V	-	-	10	nA
		$V_R = 30$ V; $T_j = 85$ °C	-	-	200	nA
$r_s$	diode series resistance	$f = 470$ MHz at $C_d = 9$ pF; see <a href="#">Figure 2</a>	-	0.65	-	$\Omega$
$C_d$	diode capacitance	$f = 1$ MHz; see <a href="#">Figure 1</a> and <a href="#">Figure 4</a>				
		$V_R = 1$ V	18.22	-	20	pF
		$V_R = 28$ V	1.9	2.1	2.25	pF
$C_{d(1V)}/C_{d(2V)}$	diode capacitance ratio (1 V to 2 V)	$f = 1$ MHz	-	1.27	-	
$C_{d(1V)}/C_{d(28V)}$	diode capacitance ratio (1 V to 28 V)	$f = 1$ MHz	8.45	9	10.9	
$C_{d(25V)}/C_{d(28V)}$	diode capacitance ratio (25 V to 28 V)	$f = 1$ MHz	-	1.05	-	
$\Delta C_d/C_d$	diode capacitance matching	$V_R = 1$ V to 28 V; in sequence of 5 diodes (gliding)	-	-	2	%



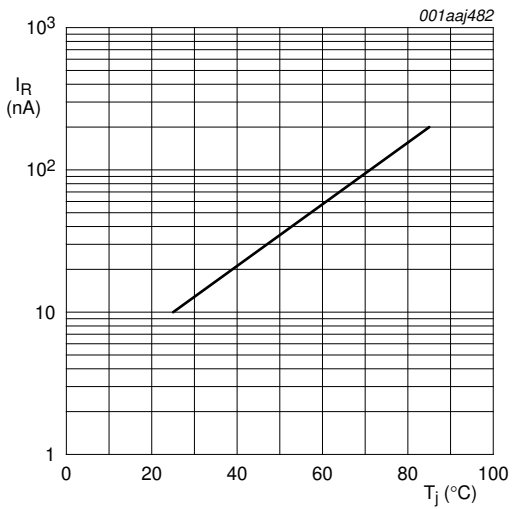
$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

**Fig 1. Diode capacitance as a function of reverse voltage; typical values**

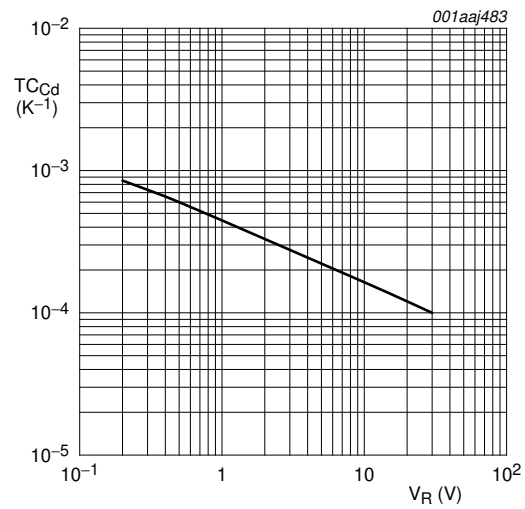


$f = 470 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

**Fig 2. Diode serial resistance as a function of reverse voltage; typical values**



**Fig 3. Reverse current as a function of junction temperature; maximum values**



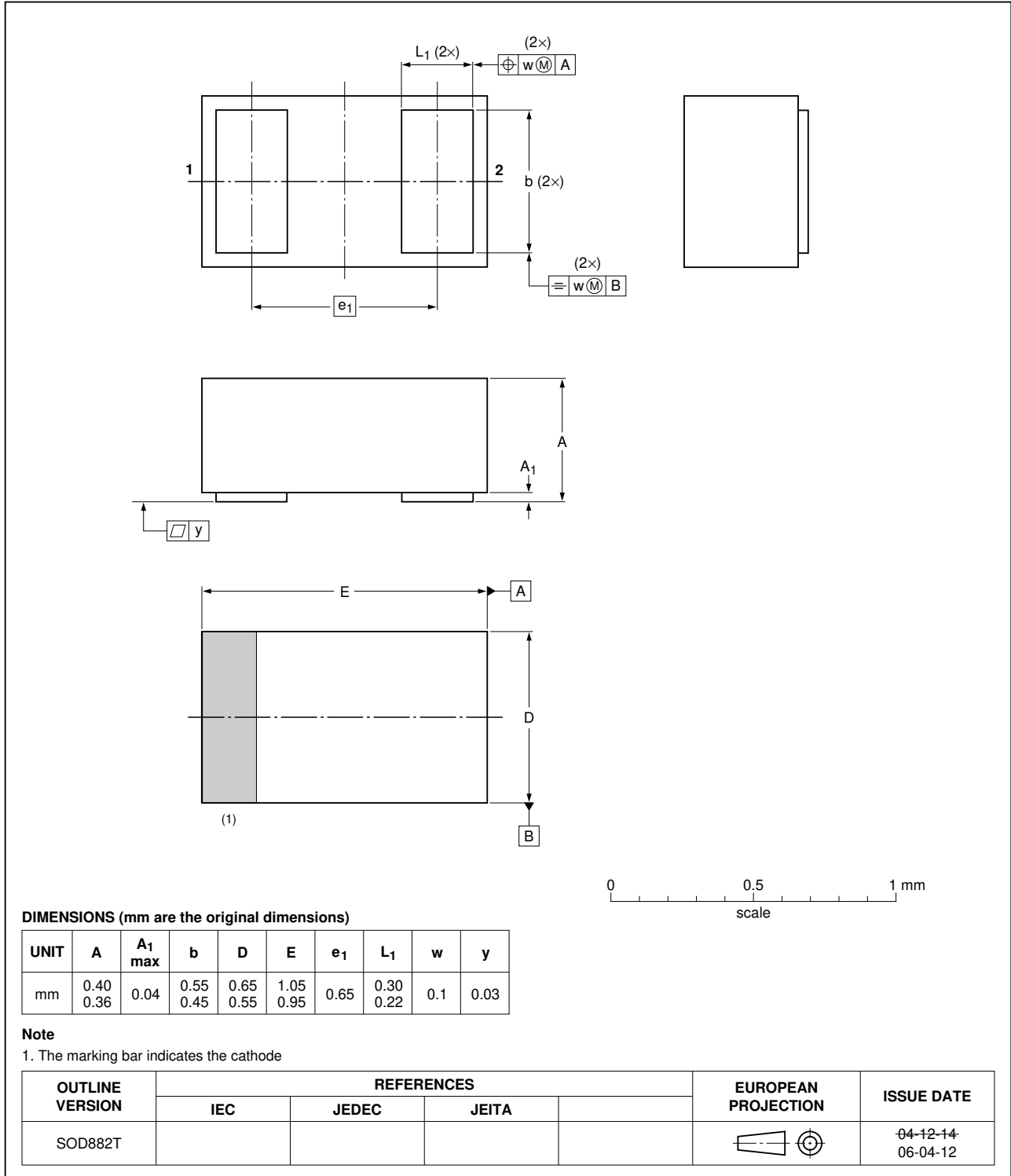
$T_j = 0 \text{ }^\circ\text{C} \text{ to } 85 \text{ }^\circ\text{C}.$

**Fig 4. Temperature coefficient of diode capacitance as a function of reverse voltage; typical values**

**7. Package outline**

Leadless ultra small plastic package; 2 terminals; body 1 x 0.6 x 0.4 mm

SOD882T



**Fig 5. Package outline SOD882T**

## 8. Abbreviations

Table 6. Abbreviations

Acronym	Description
SMD	Surface Mounted Device
UHF	Ultra High Frequency

## 9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BB179BLX v.2	20110905	Product data sheet	-	BB179BLX v.1
Modifications:		<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>		
BB179BLX v.1	20090129	Product data sheet	-	-

## 10. Legal information

### 10.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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